

17002 2812/8
PATENT
Attorney Docket No. P19-US
2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Satyadev R. Patel et al.

Art Unit: 2812

Serial No.: 10/005,308

Examiner: Not Yet Assigned

Filed: December 3, 2001

For: **METHOD FOR PERFORMING A MICRO-ELECTROMECHANICAL DEVICE**

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97(b)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached PTO form 1449. Copies of the cited references are enclosed.

This Information Disclosure Statement is being submitted after issuance of a first official action on the merits and expiration of the three month period following filing of the above-captioned application, but prior to issuance of either a final official action or a Notice of Allowance. The \$180 fee set forth in 37 CFR Section 1.17(p) is enclosed.

The above information is presented so that the Patent and Trademark Office can determine any materiality thereof to the claimed invention. It is respectfully requested that the information be expressly considered during the prosecution of this application.

10/29/2003 ZJUHR1 00000067 10005308

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The Commissioner is hereby authorized to charge any additional fee (or credit any overpayment) associated with this statement to our Deposit Account No. 501516.


Respectfully submitted,

A handwritten signature in black ink, appearing to read "Gregory R. Muir", is written over a horizontal line.

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 INFORMATION DISCLOSURE CITATION PTO-1449		ATTY. DOCKET NO. P19-US		SERIAL NO. 10/005,308			
		APPLICANT Satayadev R. Patel, et al.					
		FILING DATE 12/03/01		GROUP 2812			
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	6,072,236	06/06/00	Akram, et al.				
	5,915,168	06/22/99	Salatino, et al.				
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
Tom Glenn, et al., PACKAGING MICROSCOPIC MACHINES, MACHINE DESIGN, December 7, 2000.							
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EXAMINER		DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.





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This collection of information is required by 37 CFR 1.8. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.8 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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